

SURFACE-MOUNTING SUBSTRATE AND STRUCTURE COMPRISING
SUBSTRATE AND PART MOUNTED ON THE SUBSTRATE

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ABSTRACT OF THE DISCLOSURE

10 A surface-mounting substrate, for mounting thereon a
part such as a semiconductor device, which comprises a
core substrate, a plurality of layers of patterned wiring
lines, which are separated from each other by an
insulation layer interposed therebetween, vias piercing
15 through the insulation layer to connect the wiring lines
at the adjacent layers to each other, and a layer of
connecting terminals to mount a part on the surface-
mounting substrate, each of the connecting terminals
connecting with the wiring line at the outermost layer of
wiring lines, wherein the connecting terminal is filled
20 in an outermost insulation layer provided at the surface
of the surface-mounting substrate, and has a surface
exposed at substantially the same level as the level of
the surface of the outermost insulation layer. A
structure comprising a surface-mounting substrate and a
25 part mounted thereon, which comprises, as the substrate
used, the surface-mounting substrate of the invention, is
also disclosed.